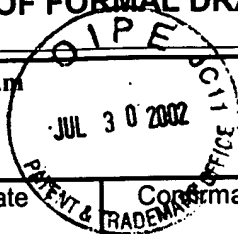


TRANSMITTAL OF FORMAL DRAWINGS

Docket No.
MCT.0012D1US (97-0141)

In Re Application Of: **Salman Akram**

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Serial No.

Filing Date

Confirmation No.

Examiner

Art Unit

09/853,111

May 10, 2001

7172

Alonzo Chambliss

2827

Invention: **METHOD OF FABRICATING MOUNTED MULTIPLE SEMICONDUCTOR DIES IN A PACKAGE**

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Transmitted herewith are:

3 sheets of formal drawing(s) for this application.

☒ Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).

[Signature]
Signature
Timothy N. Trop
Reg. No. 28,994
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Dated: 7/24/02

I certify that this document and attached formal drawings are being deposited on July 24, 2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

[Signature]
Signature of Person Mailing Correspondence

Cynthia L. Hayden

Typed or Printed Name of Person Mailing Correspondence